

### Description

Yantel's surface mount catalog bandpass filters utilize Yantel's low loss temperature stable materials which offer small size and minimal performance variation over temperature. The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

### Features

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

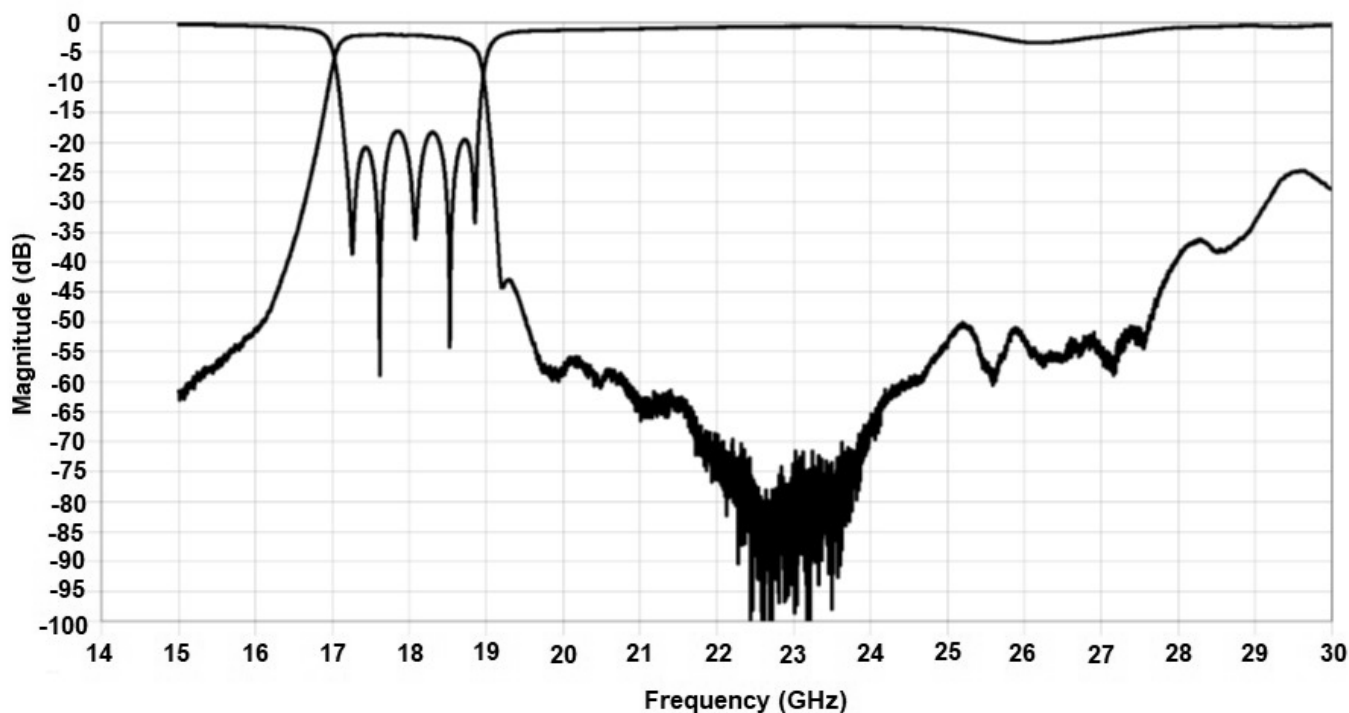
### Specifications\*

Parameter	Frequency Range (GHz)	Min	Typ.	Max
Insertion Loss (dB)	17.5 - 18.5		2.5	3.0
Return Loss (dB)		10.0	16.0	
Low Side Rejection (dB)	DC – 16.0	40.0	50.0	
High Side Rejection (dB)	19.7 - 27.5	40.0	50.0	
CW Input Power** (W)				5
$\theta_{JC} \left( \frac{^{\circ}\text{C}}{\text{W}} \right)$	15			
Size (L x W x H)	11.43 x 4.45 x 2.36 mm			

\*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary  $\pm 0.5$  dB over temperature.

\*\*Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.

### Typical Measured Performance

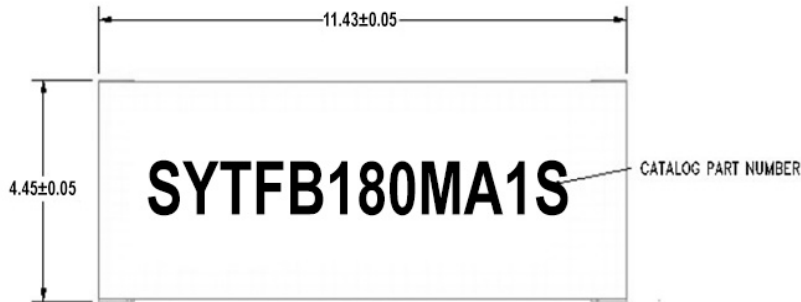


\*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00Ω CPW ground traces going into the ports at room temperature.

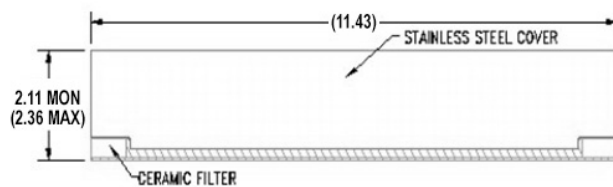
### Physical Dimensions

Units = mm

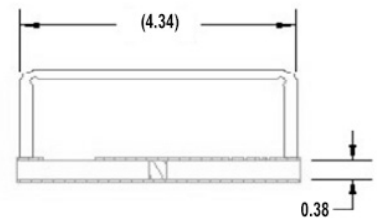
#### Top View



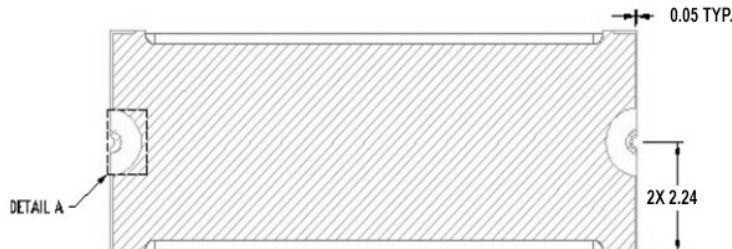
#### Side View



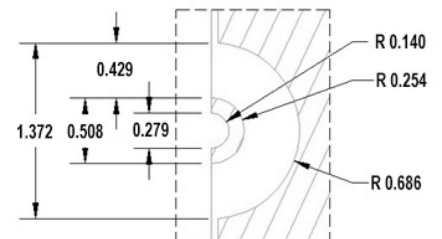
#### End View



#### Bottom View



#### DETAIL A (2 PLACES)



### Notes :

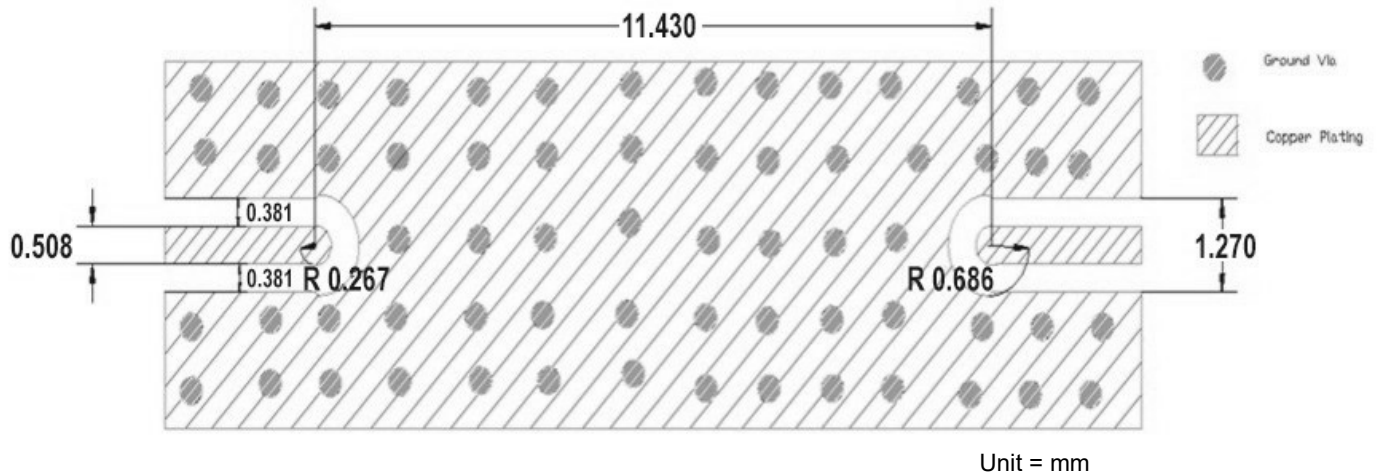
#### 1. Termination Finish:

ENIG: 76-152  $\mu\text{m}$  Au over 1270  $\mu\text{m}$  Ni

#### 2. Maximum Assembly Process Temperature: 250°C

#### 3. Dimension tolerance: $\pm 0.05$

### Recommended PCB Layout



#### Note:

- 50Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.